

• General Description

The ZM130N03L combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

- DC/DC Converters in Computing, Servers
- Isolated DC/DC Converters in Telecom and Industrial
- POL application
- BLDC Motor driver

• Ordering Information:

Part NO.	ZM130N03L
Marking	130N03
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

• Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$)

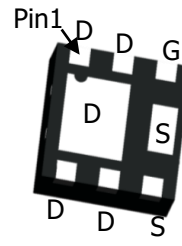
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^②	$I_{D@TC=25^\circ\text{C}}$	8	A
	$I_{D@TC=75^\circ\text{C}}$	6	A
	$I_{D@TC=100^\circ\text{C}}$	5	A
Pulsed Drain Current ^①	I_{DM}	20	A
Total Power Dissipation ^②	$P_D@TC=25^\circ\text{C}$	18	W
Total Power Dissipation	$P_D@TA=25^\circ\text{C}$	0.9	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to 150	$^\circ\text{C}$
Single Pulse Avalanche Energy@L=0.1mH	E_{AS}	20	mJ

• Product Summary


$V_{DS} = 30\text{V}$

$R_{DS(ON)} = 13\text{m}\Omega$

$I_D = 8\text{A}$



DFN2 x 2



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case ^②	R _{thJC}	-	-	36	° C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	180	° C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	° C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	30			V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} =V _{DS} , I _D =250uA	1.2		2.5	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V			1.0	uA
Gate- Source Leakage Current	I _{GSS}	V _{GS} =±12V, V _{DS} =0V			±100	nA
Static Drain-source On Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =8A		13	17	mΩ
		V _{GS} =4.5V, I _D =6A		18	24	mΩ
Forward Transconductance	g _{FS}	V _{DS} =10V, I _D =5A		9		s
Source-drain voltage	V _{SD}	I _S =8A			1.28	V

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C _{iss}	f = 1MHz	-	850	-	pF
Output capacitance	C _{oss}		-	190	-	
Reverse transfer capacitance	C _{rss}		-	100	-	

Gate Charge characteristics(T_a= 25°C)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q _g	V _{DD} =25V	-	12	-	nC
Gate - Source charge	Q _{gs}	I _D = 8A	-	4	-	
Gate - Drain charge	Q _{gd}	V _{GS} = 10V	-	8	-	

Note: ① Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% ;

② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;

Fig.1 Gate-Charge Characteristics

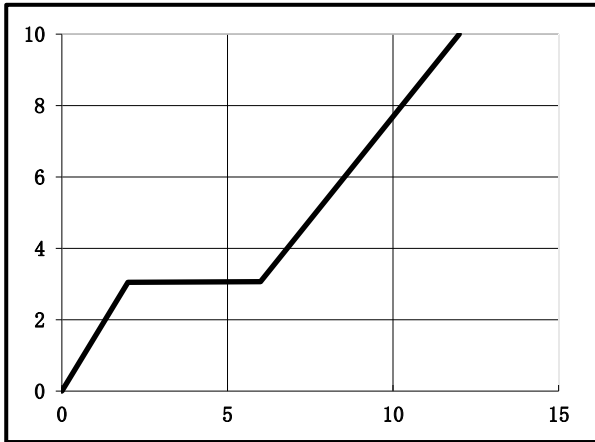


Fig.2 Capacitance Characteristics

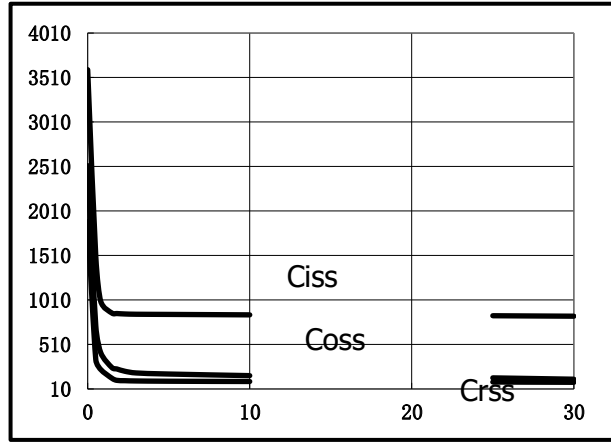


Fig.3 Power Dissipation Derating Curve

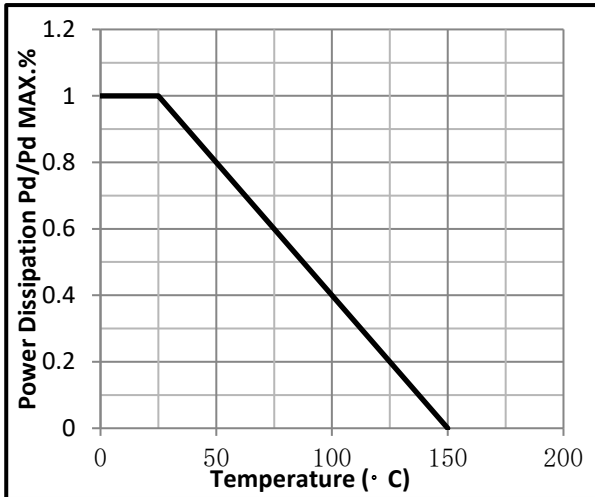


Fig.4 Typical output Characteristics

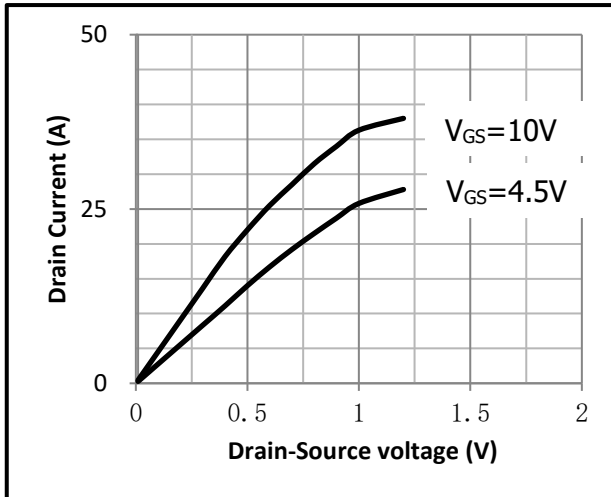


Fig.5 Threshold Voltage V.S Junction Temperature

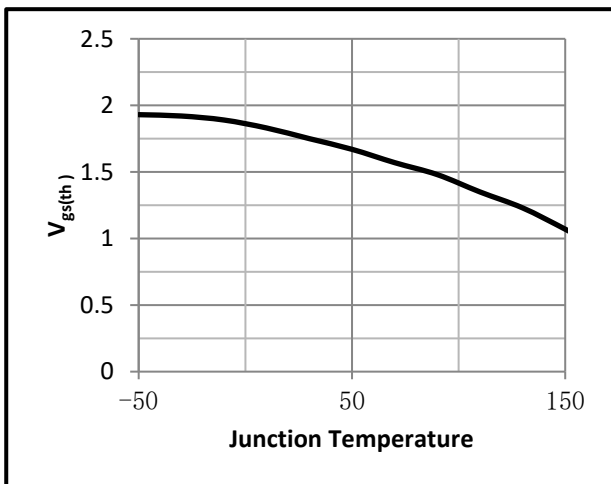


Fig.6 Resistance V.S Drain Current

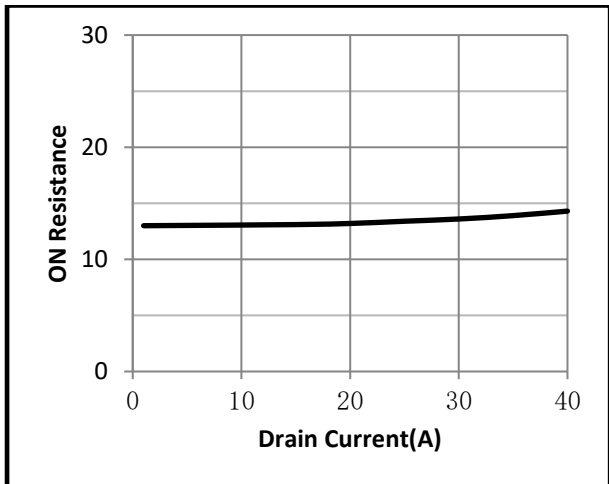


Fig.7 On-Resistance VS Gate Source Voltage

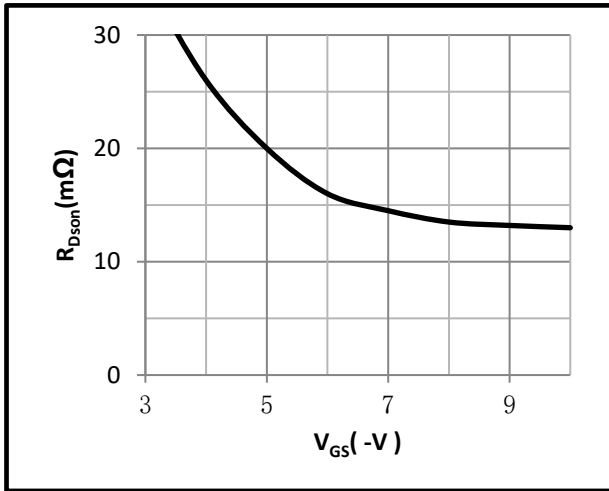


Fig.8 On-Resistance V.S Junction Temperature

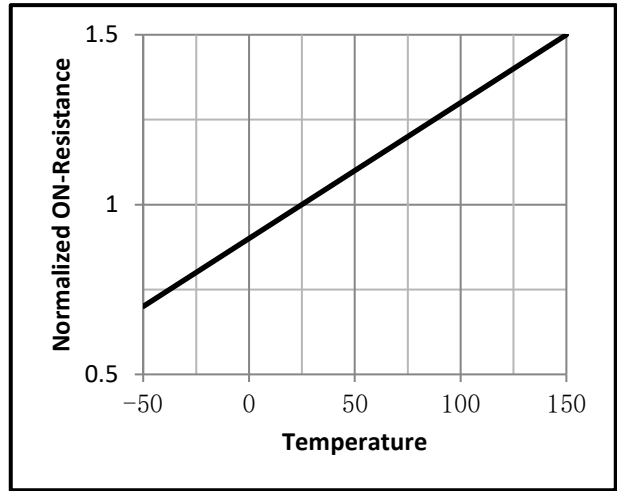


Fig.9 Switching Time Measurement Circuit

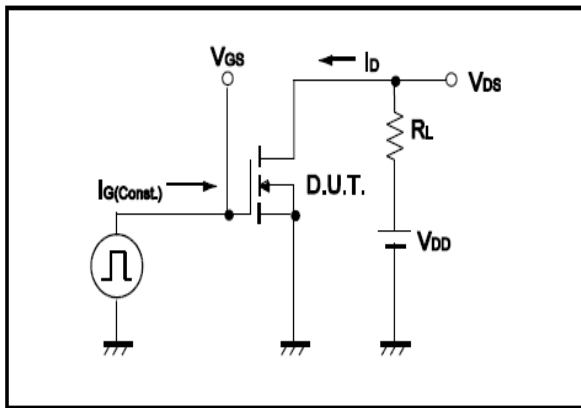


Fig.10 Gate Charge Waveform

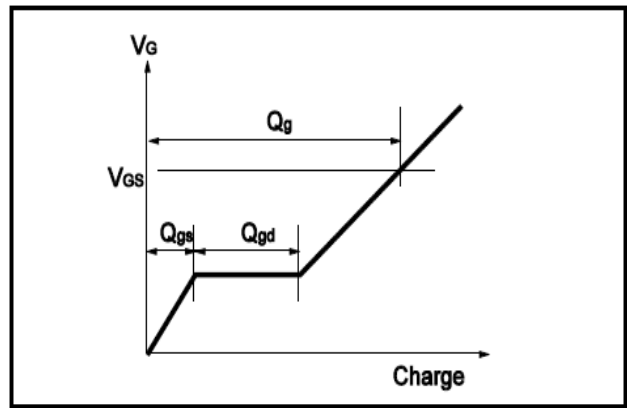


Fig.11 Switching Time Measurement Circuit

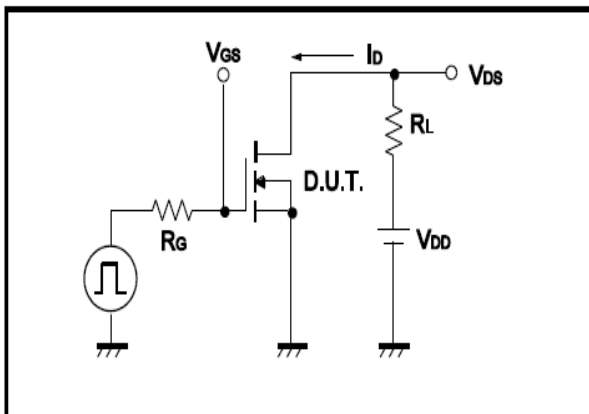
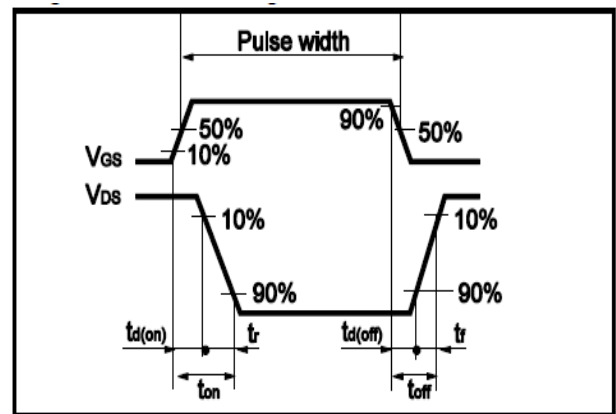


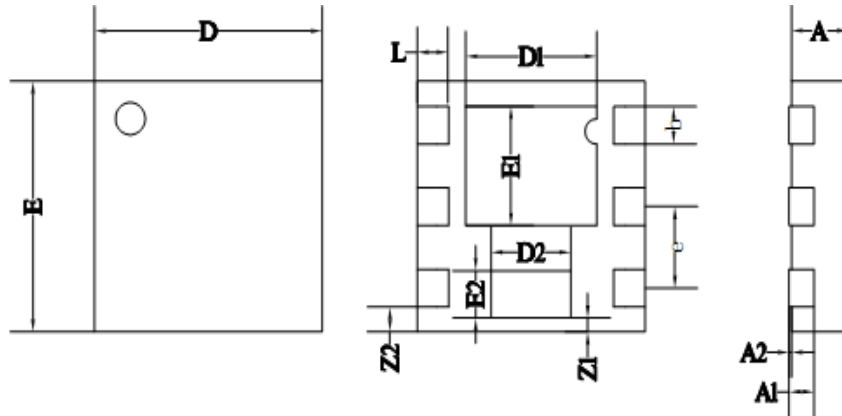
Fig.12 Gate Charge Waveform





•Dimensions(DFN2*2)

Unit: mm



NOTE:
All dimensions are in mm

	MIN	NOM	MAX
D	1.95	2.00	2.05
E	1.95	2.00	2.05
D1	1.10	1.15	1.20
E1	0.90	0.95	1.00
D2	0.65	0.70	0.75
E2	0.33	0.38	0.43
L	0.225	0.275	0.325
b	0.25	0.30	0.35
e	0.65BSC		
A	0.45	0.50	0.55
A1	0.20REF		
A2	0.00	-	0.05
Z1	0.06	0.11	0.16
Z2	0.15	0.20	0.25